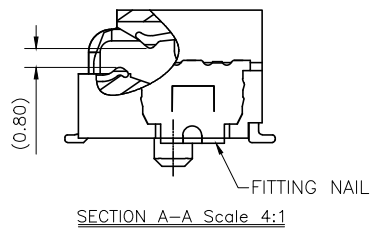
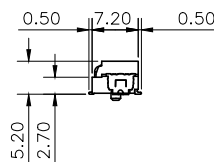
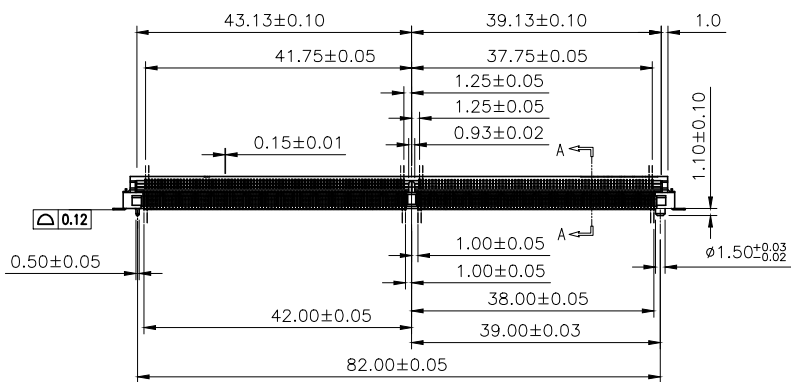
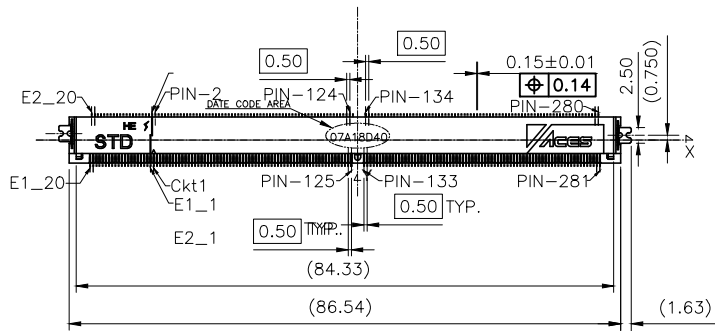




A B C D E F



- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - BOARD LOCK: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - FITTING NAIL:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - FINISH: 100~200u" MATT TIN OVER ALL
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - ROHS COMPLIANT PRODUCT.
 - SPEC. PLS. REFER TO PS-91781-xxxx
 - PACKING SPEC. PLS. REFER TO 91781-314xx(TRAY)
 - PACKING SPEC. PLS. REFER TO 91781-314xx(REEL)
 - SUGGESTION: PLS PAY ATTN TO THE DEFORMATION DIRECTION OF PCB-SMT IN CONNECTOR LAYOUT AREA
 - THE PCB WARPAGE : 0.05MAX.
 - THE PCB Coplanarity : 0.08MAX.(ex.86.54mm&CONN.LAYOUT AREA).
 - PART NUMBER

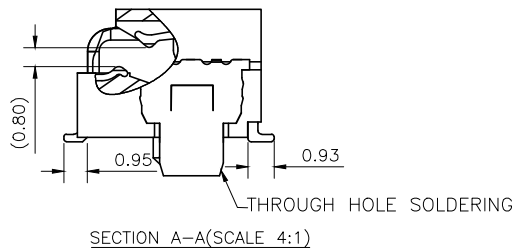
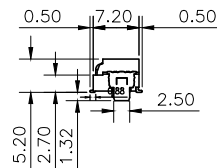
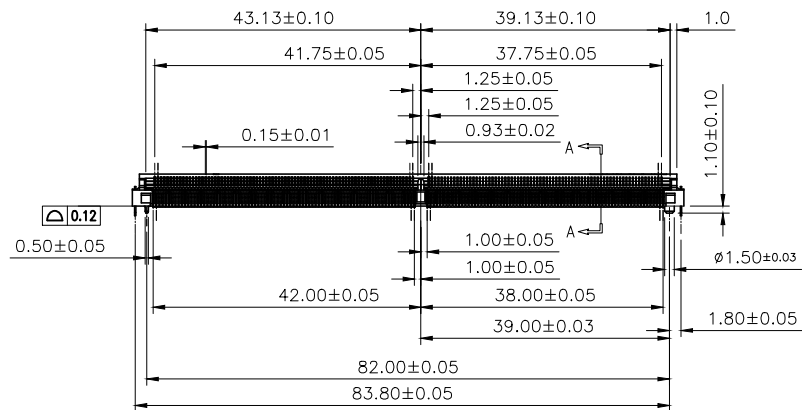
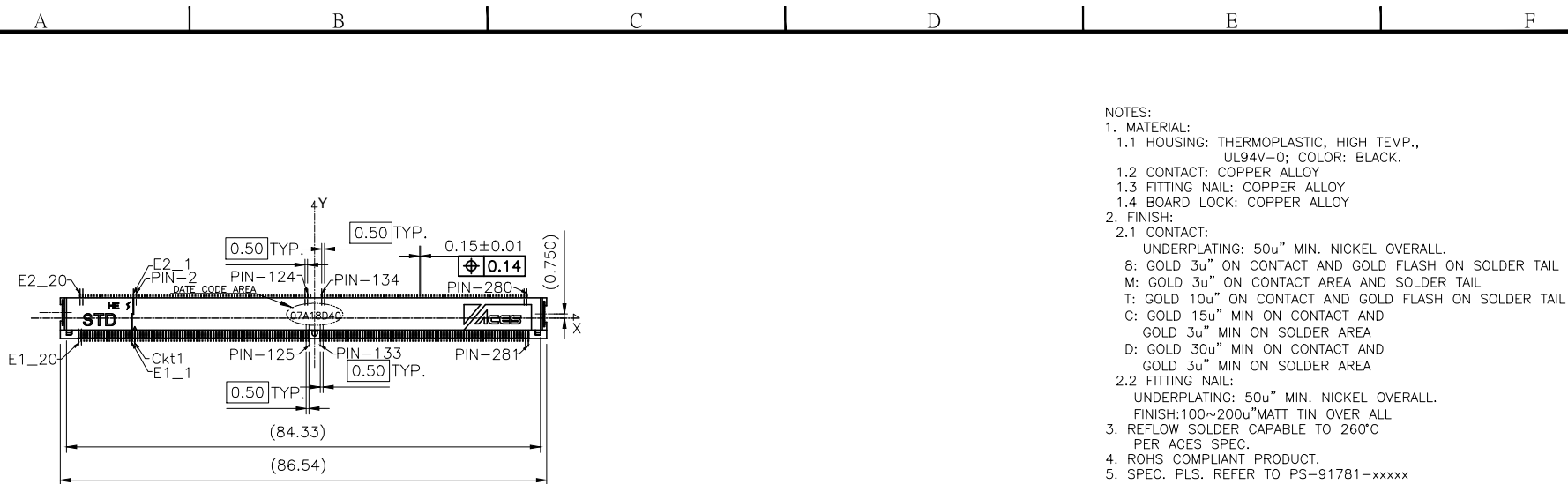
91781-XXX X X-XXX

NO OF CKT	XXX	F/N POLARIZATION
314: 314 PIN	001	SMT (SEE SHEET-1)
PACKING	002	THROUGH HOLE(SEE SHEET-2)
0:REEL		
2:TRAY		
U:REEL(PLASTIC)		

- PLATING
- 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" MIN ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY Zhang,hongjun	DATE 19/01/23	ACES ELECTRONICS	
	CHECKED BY Lu, Jing Quan	DATE 19/01/23		
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2'	APPROVED BY hsieh, fu yu	DATE 19/01/23	TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)	
	UNITS mm	SCALE 2:1	SIZE A4	DWG NO. 91781-314XX-XXX
	SHEET NO. 1 OF 5	REV E	PART NO. SEE NOTES	

B C D E F



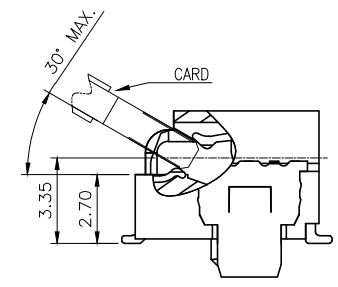
NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR: BLACK.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - 1.4 BOARD LOCK: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - 2.2 FITTING NAIL:
 - UNDERPLATING: 50u" MIN. NICKEL OVERALL.
 - FINISH: 100~200u" MATT TIN OVER ALL
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. ROHS COMPLIANT PRODUCT.
5. SPEC. PLS. REFER TO PS-91781-xxxx
6. PACKING. SPEC. PLS. REFER TO 91781-314xx(TRAY)
7. PACKING SPEC. PLS. REFER TO 91781-314xx(REEL)
8. SUGGESTION: PLS PAY ATTN TO THE DEFORMATION DIRECTION OF PCB-SMT IN CONNECTOR LAYOUT AREA
9. THE PCB WARPAGE : 0.05MAX.
10. THE PCB Coplanarity : 0.08MAX.(ex.86.54mm&CONN.LAYOUT AREA).
11. PART NUMBER

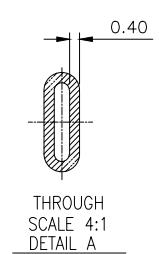
91781-XXX X X-XXX	
NO OF CKT	XXX F/N POLARIZATION
314: 314 PIN	001 SMT (SEE SHEET-1)
PACKING	002 THROUGH HOLE(SEE SHEET-2)
0: REEL	
2: TRAY	
U: REEL(PLASTIC)	

- PLATING
- 8: GOLD 3u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - M: GOLD 3u" MIN ON CONTACT AREA AND SOLDER TAIL
 - T: GOLD 10u" ON CONTACT AND GOLD FLASH ON SOLDER TAIL
 - C: GOLD 15u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA
 - D: GOLD 30u" MIN ON CONTACT AND GOLD 3u" MIN ON SOLDER AREA

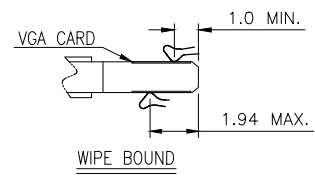
QUALITY SYMBOLS	DRAWN BY	DATE		
MAJOR	Zhang,hongjun	19/01/23		
CRITICAL	CHECKED BY	DATE	TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)	
GENERAL TOLERANCES (UNLESS SPECIFIED)	Lu, Jing Quan	19/01/23		
X. ±0.5	APPROVED BY	DATE	UNITS	SIZE
.X ±0.25	hsieh, fu yu	19/01/23	mm	A4
.XX ±0.15			SCALE	DWG NO.
.XXX ±0.1			2 : 1	91781-314XX-XXX
ANGLES ±2°			SHEET NO.	PART NO.
			2 OF 5	SEE NOTES



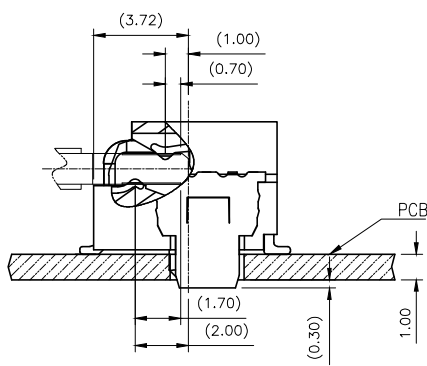
PCB 30° MAX In conn. Scale 4:1



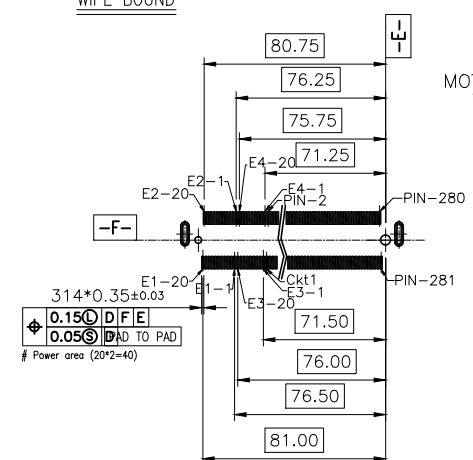
THROUGH SCALE 4:1 DETAIL A



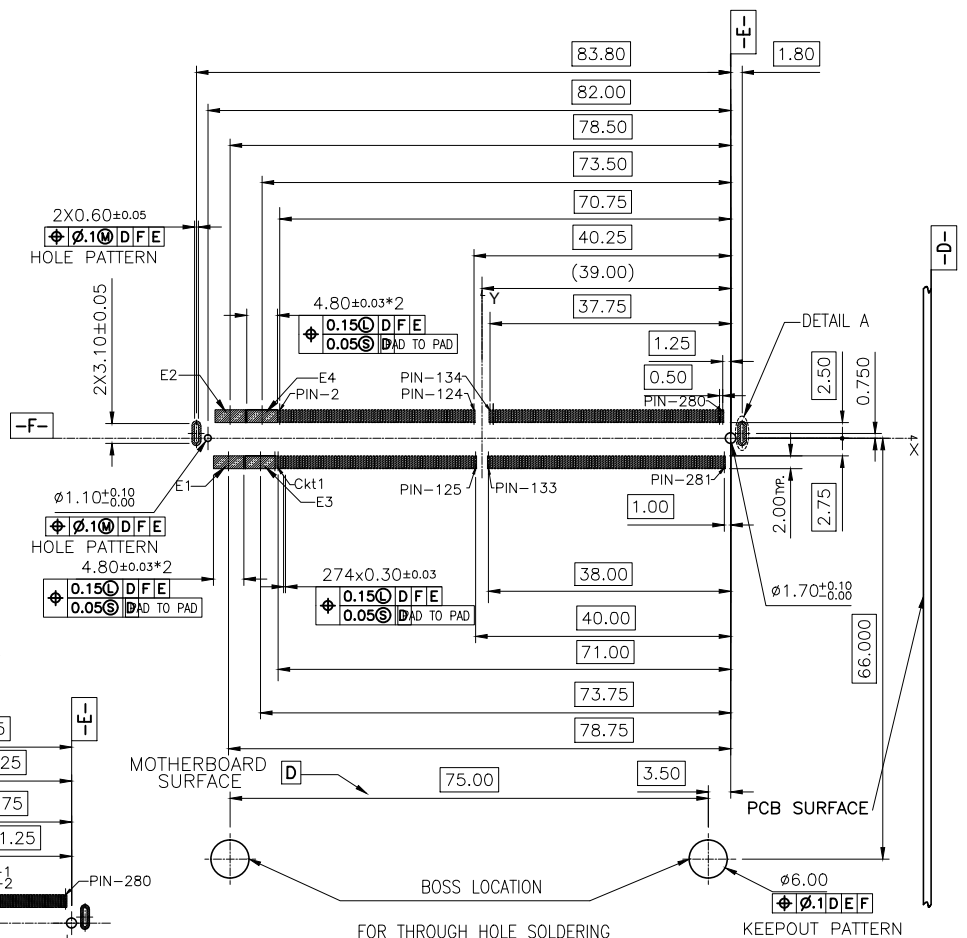
WIPE BOUND



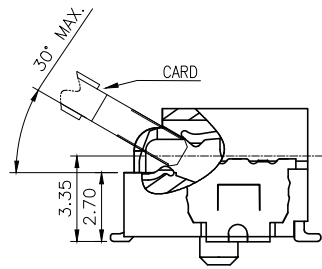
PCB on 90° Scale 4:1



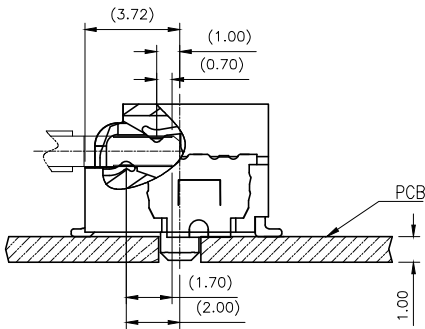
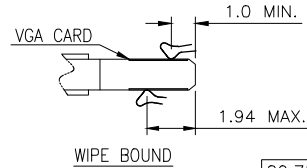
HIGH ELECTRICITY PER PIN LAYOUT



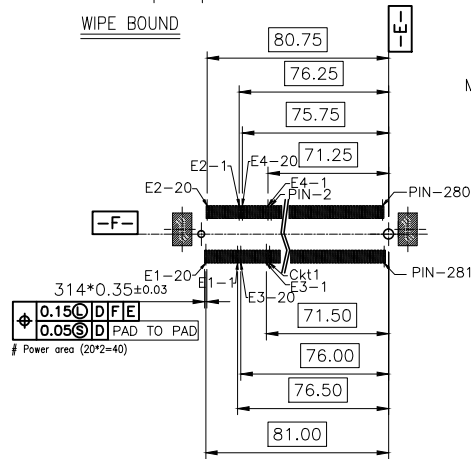
QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang, hongjun	DATE 19/01/23	
	CHECKED BY Lu, Jing Quan	DATE 19/01/23	
	APPROVED BY hsieh, fu yu	DATE 19/01/23	SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)
	UNITS mm		SIZE A4
	SCALE 2:1	SHEET NO. 3 OF 5	DWG NO. 91781-314XX-XXX
		REV E	PART NO. SEE NOTES



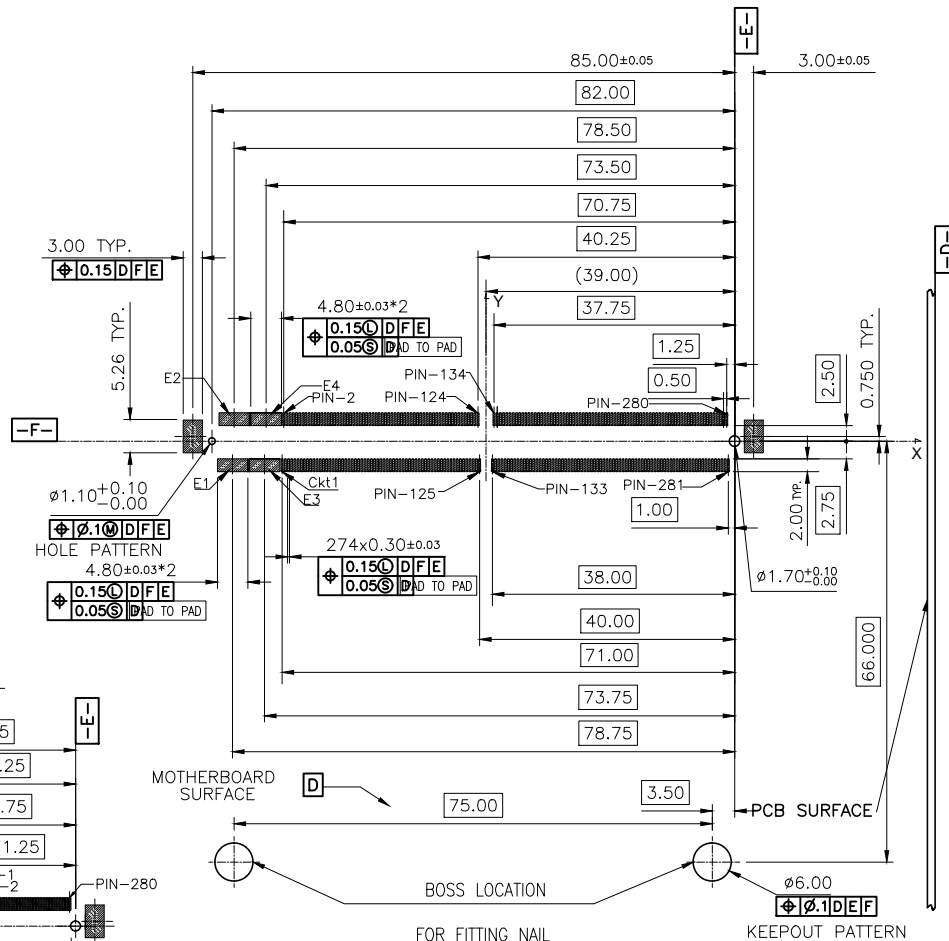
PCB 30° MAX In conn. Scale 4:1



PCB on 90° Scale 4:1



HIGH ELECTRICITY PER PIN LAYOUT



FOR FITTING NAIL
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

KEEPOUT PATTERN

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Zhang,hongjun	DATE 19/01/23		TITLE MXM-3 314 PINS 0.5mm PITCH EDGE CARD CONN. SMT D/R R/A STD TYPE H=5.2mm (BTB H=2.7)		
	CHECKED BY Lu, Jing Quan	DATE 19/01/23			UNITS mm	SIZE A4
	APPROVED BY hsieh, fu yu	DATE 19/01/23	SCALE 2:1	SHEET NO. 4 OF 5	REV E	PART NO. SEE NOTES

